

AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS
IN ASCENDING ORDER WITH STATUS INDICATOR

Please amend the following claims as indicated.

1. (Currently Amended) A process for a molded article which is shaped by molding, said process comprising:

shaping a material comprising a thermoplastic resin composition containing 100 parts by weight of a thermosetting-an amorphous-thermoplastic resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermosetting-thermoplastic resin in a die by transferring a shape of the die the inorganic compound being at least one of silica and laminar silicate, and the dispersion particle diameter of the silica being 2 μm or less and the laminar silicate having an average length of 0.01 to 3 μm and;

curing the material after shaping to obtain the molded article wherein-characterized in that not less than 75% of the shape of the a-molded article molded before curing is maintained at temperatures above the glass transition point of said thermoplastic resin.

2. (Currently Amended) A-The process for a molded article which is shaped by molding according to claim 1, wherein the thermoplastic resin composition containing 100 parts by weight of is an crystalline thermoplastic resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermoplastic resin, characterized in that not less than 75% of the shape of a molded article is maintained at temperatures above the melting point of said thermoplastic resin.

3. (Canceled).

4. (Currently Amended) The process for a molded article which is shaped by molding thermoplastic resin composition according to claim 1 or 2, wherein said inorganic compound is an inorganic compound containing silicon and oxygen as-a constituent element elements.

5. (Currently Amended) The process for a molded article which is shaped by molding thermoplastic resin composition according to claim 1 or 2, wherein said inorganic compound is laminar silicate.

6. (Currently Amended) A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition substrate comprising the molded article obtained by the process for the molded article according to claim 1 or 2.

7. (Previously Presented) A film for substrates comprising the molded article obtained by the process for the molded article, characterized in that said film is composed by using the thermoplastic resin composition according to claim 1 or 2.

8. (Canceled).

9. (Canceled).

10. (Currently Amended) The process for a molded article which is shaped by molding thermoplastic resin composition according to claim 4, wherein said inorganic compound is laminar silicate.

11. (Canceled).

12. (Currently Amended) A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition substrate comprising the molded article obtained by the process for the molded article according to claim 4.

13. (Currently Amended) A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition substrate comprising the molded article obtained by the process for the molded article according to claim 5.

14. (Canceled).

15. (Currently Amended) A film for substrates comprising the molded article obtained by the process for the molded article, ~~characterized in that said film is composed by using the thermoplastic resin composition~~ according to claim 4.

16. (Currently Amended) A film for substrates comprising the molded article obtained by the process for the molded article, ~~characterized in that said film is composed by using the thermoplastic resin composition~~ according to claim 5.